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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details	
Product Status	Obsolete
Number of LABs/CLBs	4224
Number of Logic Elements/Cells	-
Total RAM Bits	55296
Number of I/O	115
Number of Gates	250000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 70°C (TA)
Package / Case	208-BFQFP
Supplier Device Package	208-PQFP (28x28)
Purchase URL	https://www.e-xfl.com/product-detail/microsemi/ax250-1pq208

Axcelerator Family Device Status

Axcelerator® Devices	Status
AX125	Production
AX250	Production
AX500	Production
AX1000	Production
AX2000	Production

Temperature Grade Offerings

Package	AX125	AX250	AX500	AX1000	AX2000
PQ208	–	C, I, M	C, I, M	–	–
CQ208	–	M	M	–	–
CQ256	–	–	–	–	M
FG256	C, I	C, I, M	–	–	–
FG324	C, I	–	–	–	–
CQ352	–	M	M	M	M
FG484	–	C, I, M	C, I, M	C, I, M	–
CG624	–	–	–	M	M
FG676	–	–	C, I, M	C, I, M	–
BG729	–	–	–	C, I, M	–
FG896	–	–	–	C, I, M	C, I, M
FG1152	–	–	–	–	C, I, M

C = Commercial

I = Industrial

M = Military

Speed Grade and Temperature Grade Matrix

Temperature Grade	Std	–1	–2
C	✓	✓	✓
I	✓	✓	✓
M	✓	✓	–

C = Commercial

I = Industrial

M = Military

2 – Detailed Specifications

Operating Conditions

Table 2-1 lists the absolute maximum ratings of Axcelerator devices. Stresses beyond the ratings may cause permanent damage to the device. Exposure to Absolute Maximum rated conditions for extended periods may affect device reliability. Devices should not be operated outside the recommendations in Table 2-2.

***Table 2-1* • Absolute Maximum Ratings**

Symbol	Parameter	Limits	Units
VCCA	DC Core Supply Voltage	–0.3 to 1.7	V
VCCI	DC I/O Supply Voltage	–0.3 to 3.75	V
VREF	DC I/O Reference Voltage	–0.3 to 3.75	V
VI	Input Voltage	–0.5 to 4.1	V
VO	Output Voltage	–0.5 to 3.75	V
TSTG	Storage Temperature	–60 to +150	°C
VCCDA*	Supply Voltage for Differential I/Os	–0.3 to 3.75	V

*Note: * Should be the maximum of all VCCI.*

***Table 2-2* • Recommended Operating Conditions**

Parameter Range	Commercial	Industrial	Military	Units
Ambient Temperature (T_A)[1]	0 to +70	–40 to +85	–55 to +125	°C
1.5 V Core Supply Voltage	1.425 to 1.575	1.425 to 1.575	1.425 to 1.575	V
1.5 V I/O Supply Voltage	1.425 to 1.575	1.425 to 1.575	1.425 to 1.575	V
1.8 V I/O Supply Voltage	1.71 to 1.89	1.71 to 1.89	1.71 to 1.89	V
2.5 V I/O Supply Voltage	2.375 to 2.625	2.375 to 2.625	2.375 to 2.625	V
3.3 V I/O Supply Voltage	3.0 to 3.6	3.0 to 3.6	3.0 to 3.6	V
VCCDA Supply Voltage	3.0 to 3.6	3.0 to 3.6	3.0 to 3.6	V
VPUMP Supply Voltage	3.0 to 3.6	3.0 to 3.6	3.0 to 3.6	V

Notes:

1. *Ambient temperature (T_A) is used for commercial and industrial grades; case temperature (T_C) is used for military grades.*
2. *T_J max = 125°C*

Power-Up/Down Sequence

All Axcelerator I/Os are tristated during power-up until normal device operating conditions are reached, when I/Os enter user mode. VCCDA should be powered up before (or coincidentally with) VCCA and VCCI to ensure the behavior of user I/Os at system start-up. Conversely, VCCDA should be powered down after (or coincidentally with) VCCA and VCCI. Note that VCCI and VCCA can be powered up in any sequence with respect to each other, provided the requirement with respect to VCCDA is satisfied.

Table 2-4 • **Default CLOAD/VCCI**

	C_{LOAD} (pF)	VCCI (V)	PLOAD (mw/MHz)	P10 (mw/MHz)	PI/O (mW/MHz)*
Single-Ended without VREF					
LVTTL 24 mA High Slew	35	3.3	381.2	267.5	648.7
LVTTL 16 mA High Slew	35	3.3	381.2	225.1	606.3
LVTTL 12 mA High Slew	35	3.3	381.2	165.9	547.1
LVTTL 8 mA High Slew	35	3.3	381.2	130.3	511.5
LVTTL 24 mA Low Slew	35	3.3	381.2	169.2	550.4
LVTTL 16 mA Low Slew	35	3.3	381.2	150.8	532.0
LVTTL 12 mA Low Slew	35	3.3	381.2	138.6	519.8
LVTTL 8 mA Low Slew	35	3.3	381.2	118.7	499.9
LVCMOS – 25	35	2.5	218.8	148.0	366.8
LVCMOS – 18	35	1.8	113.4	73.4	186.8
LVCMOS – 15 (JESD8-11)	35	1.5	78.8	49.5	128.3
PCI	10	3.3	108.9	218.5	327.4
PCI-X	10	3.3	108.9	162.9	271.8
Single-Ended with VREF					
HSTL-I	20	1.5	–	40.9	40.9
SSTL2-I	30	2.5	–	171.2	171.2
SSTL2-II	30	2.5	–	147.8	147.8
SSTL3-I	30	3.3	–	327.2	327.2
SSTL3-II	30	3.3	–	288.4	288.4
GTLP – 25	10	2.5	–	61.5	61.5
GTLP – 33	10	3.3	–	68.5	68.5
Differential					
LVPECL – 33	N/A	3.3	–	260.6	260.6
LVDS – 25	N/A	2.5	–	145.8	145.8

Note: $*P_{I/O} = P10 + C_{LOAD} * VCCI^2$

Thermal Characteristics

Introduction

The temperature variable in Microsemi's Designer software refers to the junction temperature, not the ambient temperature. This is an important distinction because dynamic and static power consumption cause the chip junction temperature to be higher than the ambient temperature. EQ 1 can be used to calculate junction temperature.

$$T_J = \text{Junction Temperature} = \Delta T + T_a$$

EQ 1

Where:

T_a = Ambient Temperature

ΔT = Temperature gradient between junction (silicon) and ambient

$$\Delta T = \theta_{ja} * P$$

EQ 2

Where:

P = Power

θ_{ja} = Junction to ambient of package. θ_{ja} numbers are located under Table 2-6 on page 2-7.

Package Thermal Characteristics

The device junction-to-case thermal characteristic is θ_{jc}, and the junction-to-ambient air characteristic is θ_{ja}. The thermal characteristics for θ_{ja} are shown with two different air flow rates. θ_{jc} values are provided for reference. The absolute maximum junction temperature is 125°C.

The maximum power dissipation allowed for commercial- and industrial-grade devices is a function of θ_{ja}. A sample calculation of the absolute maximum power dissipation allowed for an 896-pin FBGA package at commercial temperature and still air is as follows:

$$\text{Maximum Power Allowed} = \frac{\text{Max. junction temp. (°C)} - \text{Max. ambient temp. (°C)}}{\theta_{ja}\text{(°C/W)}} = \frac{125°C - 70°C}{13.6°C/W} = 4.04\text{ W}$$

The maximum power dissipation allowed for Military temperature and Mil-Std 883B devices is specified as a function of θ_{jc}.

Table 2-6 • **Package Thermal Characteristics**

Package Type	Pin Count	θ_{jc}	θ_{ja} Still Air	θ_{ja} 1.0m/s	θ_{ja} 2.5m/s	Units
Chip Scale Package (CSP)	180	N/A	57.8	51.0	50	°C/W
Plastic Quad Flat Pack (PQFP)	208	8.0	26	23.5	20.9	°C/W
Plastic Ball Grid Array (PBGA)	729	2.2	13.7	10.6	9.6	°C/W
Fine Pitch Ball Grid Array (FBGA)	256	3.0	26.6	22.8	21.5	°C/W
Fine Pitch Ball Grid Array (FBGA)	324	3.0	25.8	22.1	20.9	°C/W
Fine Pitch Ball Grid Array (FBGA)	484	3.2	20.5	17.0	15.9	°C/W
Fine Pitch Ball Grid Array (FBGA)	676	3.2	16.4	13.0	12.0	°C/W
Fine Pitch Ball Grid Array (FBGA)	896	2.4	13.6	10.4	9.4	°C/W
Fine Pitch Ball Grid Array (FBGA)	1152	1.8	12.0	8.9	7.9	°C/W
Ceramic Quad Flat Pack (CQFP)[1]	208	2.0	22	19.8	18.0	°C/W
Ceramic Quad Flat Pack (CQFP)[1]	352	2.0	17.9	16.1	14.7	°C/W
Ceramic Column Grid Array (CCGA)[2]	624	6.5	8.9	8.5	8	°C/W

Notes:

1. *θ_{jc} for the 208-pin and 352-pin CQFP refers to the thermal resistance between the junction and the bottom of the package.*
2. *θ_{jc} for the 624-pin CCGA refers to the thermal resistance between the junction and the top surface of the package. Thermal resistance from junction to board (θ_{jb}) for CCGA 624 package is 3.4°C/W.*

Timing Characteristics

Axcelerator devices are manufactured in a CMOS process, therefore, device performance varies according to temperature, voltage, and process variations. Minimum timing parameters reflect maximum operating voltage, minimum operating temperature, and best-case processing. Maximum timing parameters reflect minimum operating voltage, maximum operating temperature, and worst-case processing. The derating factors shown in Table 2-7 should be applied to all timing data contained within this datasheet.

Table 2-7 • **Temperature and Voltage Timing Derating Factors (Normalized to Worst-Case Commercial, T_J = 70°C, VCCA = 1.425V)**

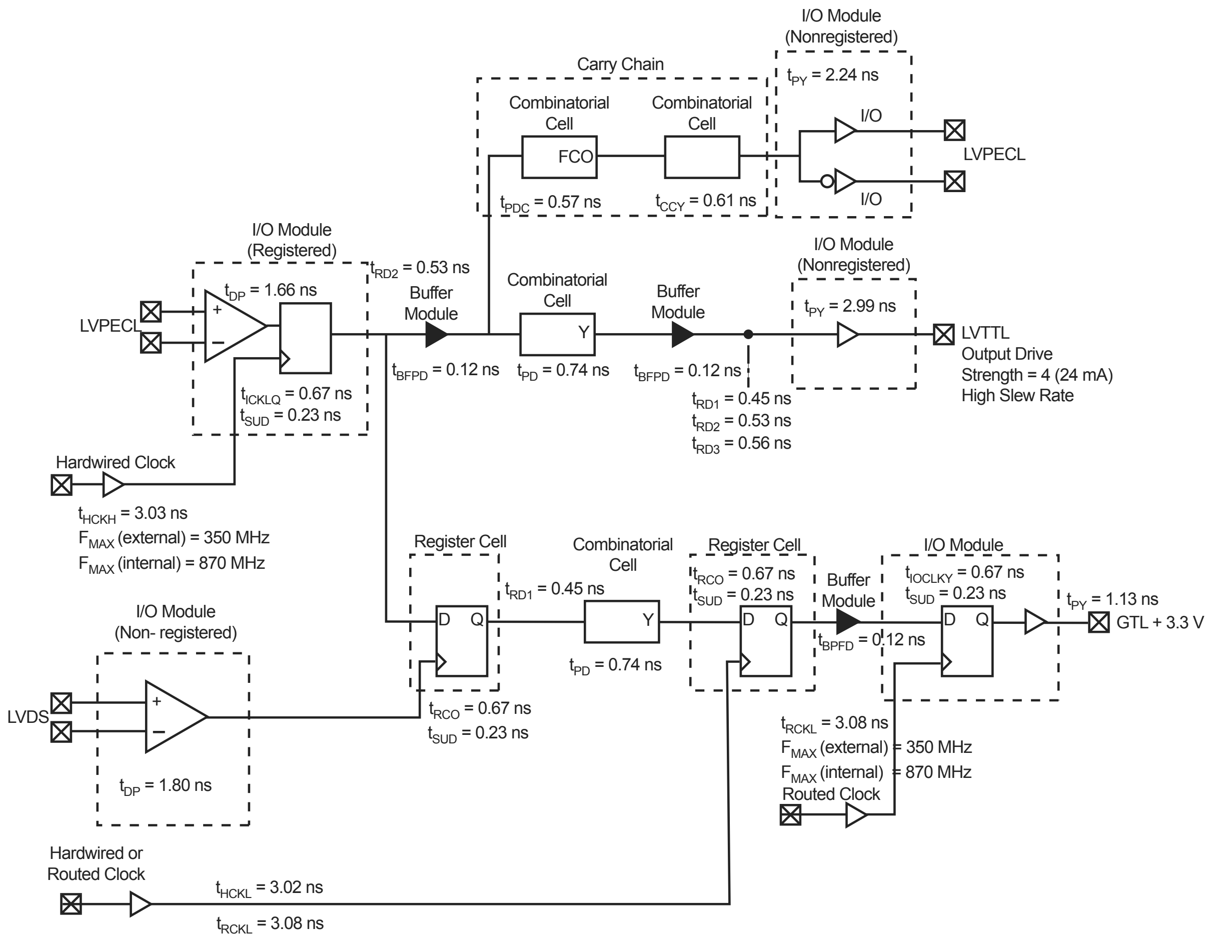
	Junction Temperature						
VCCA	**–55°C**	**–40°C**	**0°C**	**25°C**	**70°C**	**85°C**	**125°C**
1.4 V	0.83	0.86	0.91	0.96	1.02	1.05	1.15
1.425 V	0.82	0.84	0.90	0.94	1.00	1.04	1.13
1.5 V	0.78	0.80	0.85	0.89	0.95	0.98	1.07
1.575 V	0.74	0.76	0.81	0.85	0.90	0.94	1.02
1.6 V	0.73	0.75	0.80	0.84	0.89	0.92	1.01

Notes:

1. *The user can set the junction temperature in Designer software to be any integer value in the range of –55°C to 175°C.*
2. *The user can set the core voltage in Designer software to be any value between 1.4V and 1.6V.*

All timing numbers listed in this datasheet represent sample timing characteristics of Axcelerator devices. Actual timing delay values are design-specific and can be derived from the Timer tool in Microsemi's Designer software after place-and-route.

Timing Model



Note: Worst case timing data for the AX1000, –2 speed grade

Figure 2-1 • **Worst Case Timing Data**

Hardwired Clock – Using LVTTL 24 mA High Slew Clock I/O

External Setup

$= (t_{DP} + t_{RD2} + t_{SUD}) - t_{HCKL}$

= (1.72 + 0.53 + 0.23) – 3.02 = –0.54 ns

Clock-to-Out (Pad-to-Pad)

$= t_{HCKL} + t_{RCO} + t_{RD1} + t_{PY}$

= 3.02 + 0.67 + 0.45 + 2.99 = 7.13 ns

Routed Clock – Using LVTTL 24 mA High Slew Clock I/O

External Setup

$= (t_{DP} + t_{RD2} + t_{SUD}) - t_{RCKH}$

= (1.72 + 0.53 + 0.23) – 3.13 = –0.65 ns

Clock-to-Out (Pad-to-Pad)

$= t_{RCKH} + t_{RCO} + t_{RD1} + t_{PY}$

= 3.13 + 0.67 + 0.45 + 3.03 = 7.24 ns

Table 2-22 **• 3.3 V LVTTL I/O Module**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C (continued)

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
LVTTL Output Drive Strength = 4 (24 mA) / Low Slew Rate								
t_{DP}	Input Buffer		1.68		1.92		2.26	ns
t_{PY}	Output Buffer		10.45		11.90		13.99	ns
t_{ENZL}	Enable to Pad Delay through the Output Buffer—Z to Low		10.61		12.08		14.21	ns
t_{ENZH}	Enable to Pad Delay through the Output Buffer—Z to High		10.47		11.93		14.02	ns
t_{ENLZ}	Enable to Pad Delay through the Output Buffer—Low to Z		1.92		1.94		1.94	ns
t_{ENHZ}	Enable to Pad Delay through the Output Buffer—High to Z		2.57		2.58		2.59	ns
t_{IOCLKQ}	Sequential Clock-to-Q for the I/O Input Register		0.67		0.77		0.90	ns
t_{IOCLKY}	Clock-to-output Y for the I/O Output Register and the I/O Enable Register		0.67		0.77		0.90	ns
t_{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t_{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t_{HD}	Data Input Hold		0.00		0.00		0.00	ns
t_{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t_{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t_{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t_{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t_{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t_{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t_{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t_{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

Table 2-22 **• 3.3 V LVTTL I/O Module**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C (continued)

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
LVTTL Output Drive Strength = 1 (8 mA) / High Slew Rate								
t_{DP}	Input Buffer		1.68		1.92		2.26	ns
t_{PY}	Output Buffer		4.23		4.81		5.66	ns
t_{ENZL}	Enable to Pad Delay through the Output Buffer—Z to Low		4.64		5.28		6.21	ns
t_{ENZH}	Enable to Pad Delay through the Output Buffer—Z to High		4.23		4.81		5.66	ns
t_{ENLZ}	Enable to Pad Delay through the Output Buffer—Low to Z		1.89		1.91		1.91	ns
t_{ENHZ}	Enable to Pad Delay through the Output Buffer—High to Z		2.01		2.02		2.03	ns
t_{IOCLKQ}	Sequential Clock-to-Q for the I/O Input Register		0.67		0.77		0.90	ns
t_{IOCLKY}	Clock-to-output Y for the I/O Output Register and the I/O Enable Register		0.67		0.77		0.90	ns
t_{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t_{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t_{HD}	Data Input Hold		0.00		0.00		0.00	ns
t_{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t_{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t_{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t_{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t_{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t_{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t_{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t_{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

Timing Characteristics

Table 2-32 • 1.5V LVCMOS I/O Module
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 1.4 V, TJ = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
LVCMOS15 (JESD8-11) I/O Module Timing								
t_{DP}	Input Buffer		3.59		4.09		4.81	ns
t_{PY}	Output Buffer		6.05		6.89		8.10	ns
t_{ENZL}	Enable to Pad Delay through the Output Buffer—Z to Low		3.31		3.34		3.34	ns
t_{ENZH}	Enable to Pad Delay through the Output Buffer—Z to High		4.56		4.58		4.59	ns
t_{ENLZ}	Enable to Pad Delay through the Output Buffer—Low to Z		6.37		7.25		8.52	ns
t_{ENHZ}	Enable to Pad Delay through the Output Buffer—High to Z		6.94		7.90		9.29	ns
t_{IOCLKQ}	Sequential Clock-to-Q for the I/O Input Register		0.67		0.77		0.90	ns
t_{IOCLKY}	Clock-to-output Y for the I/O Output Register and the I/O Enable Register		0.67		0.77		0.90	ns
t_{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t_{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t_{HD}	Data Input Hold		0.00		0.00		0.00	ns
t_{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t_{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t_{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t_{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t_{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t_{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t_{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t_{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

Differential Standards

Physical Implementation

Implementing differential I/O standards requires the configuration of a pair of external I/O pads, resulting in a single internal signal. To facilitate construction of the differential pair, a single I/O Cluster contains the resources for a pair of I/Os. Configuration of the I/O Cluster as a differential pair is handled by Designer software when the user instantiates a differential I/O macro in the design.

Differential I/Os can also be used in conjunction with the embedded Input Register (InReg), Output Register (OutReg), Enable Register (EnReg), and Double Data Rate (DDR). However, there is no support for bidirectional I/Os or tristates with these standards.

LVDS

Low-Voltage Differential Signal (ANSI/TIA/EIA-644) is a high-speed, differential I/O standard. It requires that one data bit is carried through two signal lines, so two pins are needed. It also requires an external resistor termination. The voltage swing between these two signal lines is approximately 350 mV.

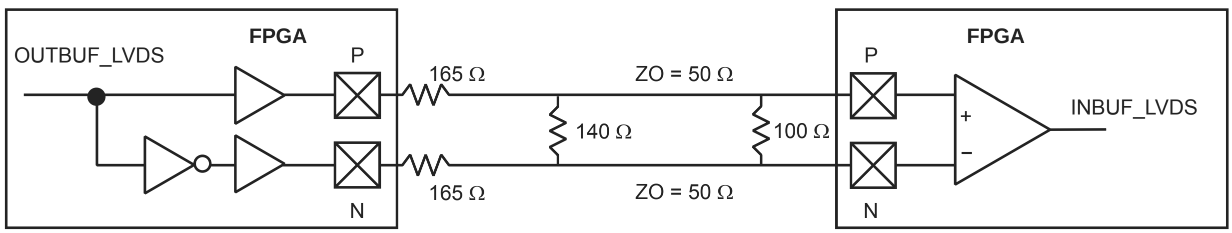


***Figure 2-25* • LVDS Board-Level Implementation**

The LVDS circuit consists of a differential driver connected to a terminated receiver through a constant-impedance transmission line. The receiver is a wide-common-mode-range differential amplifier. The common-mode range is from 0.2 V to 2.2 V for a differential input with 400 mV swing.

To implement the driver for the LVDS circuit, drivers from two adjacent I/O cells are used to generate the differential signals (note that the driver is not a current-mode driver). This driver provides a nominal constant current of 3.5 mA. When this current flows through a 100 Ω termination resistor on the receiver side, a voltage swing of 350 mV is developed across the resistor. The direction of the current flow is controlled by the data fed to the driver.

An external-resistor network (three resistors) is needed to reduce the voltage swing to about 350 mV. Therefore, four external resistors are required, three for the driver and one for the receiver.

***Table 2-56* • DC Input and Output Levels**

DC Parameter	Description	Min.	Typ.	Max.	Units
VCCI[1]	Supply Voltage	2.375	2.5	2.625	V
VOH	Output High Voltage	1.25	1.425	1.6	V
VOL	Output Low Voltage	0.9	1.075	1.25	V
VODIFF	Differential Output Voltage	250	350	450	mV
VOCM	Output Common Mode Voltage	1.125	1.25	1.375	V
VICM2	Input Common Mode Voltage	0.2	1.25	2.2	V

Notes:

1. *±5%*
2. *Differential input voltage = ±350 mV.*

Table 2-101 • Eight FIFO Blocks Cascaded
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
FIFO Module Timing								
t_{WSU}	Write Setup		15.46		17.61		20.70	ns
t_{WHD}	Write Hold		0.00		0.00		0.00	ns
t_{WCKH}	WCLK High		0.75		0.75		0.75	ns
t_{WCKL}	WCLK Low		5.13		5.13		5.13	ns
t_{WCKP}	Minimum WCLK Period	5.88		5.88		5.88		ns
t_{RSU}	Read Setup		16.22		18.47		21.72	ns
t_{RHD}	Read Hold		0.00		0.00		0.00	ns
t_{RCKH}	RCLK High		0.73		0.73		0.73	ns
t_{RCKL}	RCLK Low		5.77		5.77		5.77	ns
t_{RCKP}	Minimum RCLK period	6.50		6.50		6.50		ns
t_{CLRHF}	Clear High		0.00		0.00		0.00	ns
t_{CLR2FF}	Clear-to-flag (EMPTY/FULL)		1.92		2.18		2.57	ns
t_{CLR2AF}	Clear-to-flag (AEMPTY/AFULL)		4.39		5.00		5.88	ns
t_{CK2FF}	Clock-to-flag (EMPTY/FULL)		2.13		2.42		2.85	ns
t_{CK2AF}	Clock-to-flag (AEMPTY/AFULL)		5.04		5.75		6.75	ns
$t_{RCK2RD1}$	RCLK-To-OUT (Pipelined)		3.39		3.86		4.54	ns
$t_{RCK2RD2}$	RCLK-To-OUT (Nonpipelined)		4.93		5.62		6.61	ns

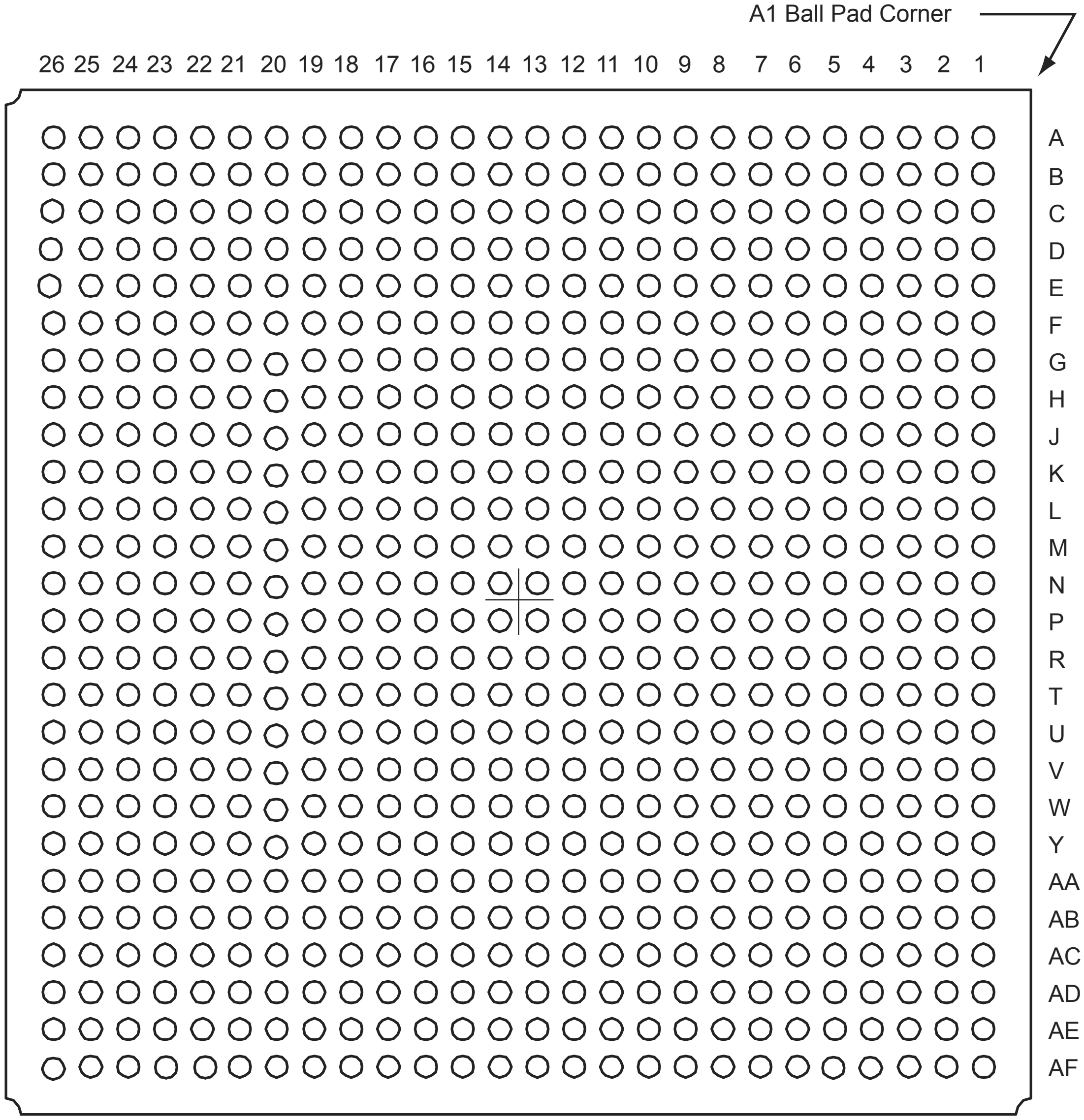
Note: Timing data for these eight cascaded FIFO blocks uses a depth of 32,768. For all other combinations, use Microsemi's timing software.

FG484	
AX500 Function	Pin Number
IO108PB5F10	AA10
IO110NB5F10	AB9
IO110PB5F10	AB10
IO111NB5F10	Y8
IO111PB5F10	Y9
IO112NB5F10	AB7
IO113NB5F10	W8
IO113PB5F10	W9
IO114NB5F11	AA7
IO114PB5F11	AA8
IO115NB5F11	AB5
IO115PB5F11	AB6
IO116NB5F11	Y6
IO116PB5F11	Y7
IO117NB5F11	U8
IO117PB5F11	U9
IO118NB5F11	AA5
IO118PB5F11	AA6
IO119NB5F11	AA4
IO119PB5F11	AB4
IO120NB5F11	Y4
IO120PB5F11	Y5
IO121NB5F11	W6
IO121PB5F11	W7
IO122NB5F11	V3
IO122PB5F11	W3
IO123NB5F11	T7
IO123PB5F11	T8
IO124NB5F11	V4
IO124PB5F11	W5
IO125NB5F11	V6
IO125PB5F11	V7
Bank 6	
IO126NB6F12	V2
IO126PB6F12	W2

FG484	
AX500 Function	Pin Number
IO127NB6F12	P7
IO127PB6F12	R7
IO128NB6F12	V1
IO128PB6F12	W1
IO129NB6F12	U5
IO129PB6F12	T5
IO130NB6F12	T1
IO130PB6F12	U1
IO131NB6F12	P6
IO131PB6F12	R6
IO132NB6F12	T4
IO132PB6F12	U4
IO133NB6F12	U2
IO134NB6F12	T3
IO134PB6F12	U3
IO135NB6F12	P5
IO135PB6F12	R5
IO136NB6F13	R2
IO136PB6F13	T2
IO138NB6F13	P4
IO138PB6F13	R4
IO139NB6F13	N2
IO139PB6F13	P2
IO140NB6F13	P3
IO140PB6F13	R3
IO141NB6F13	M6
IO141PB6F13	N6
IO142NB6F13	P1
IO142PB6F13	R1
IO143NB6F13	M5
IO143PB6F13	N5
IO144NB6F13	M4
IO144PB6F13	N4
IO145NB6F13	M7
IO145PB6F13	N7

FG484	
AX500 Function	Pin Number
IO146NB6F13	M3
IO146PB6F13	N3
Bank 7	
IO147NB7F14	K7
IO147PB7F14	L7
IO148NB7F14	M2
IO148PB7F14	N1
IO149NB7F14	K5
IO149PB7F14	L5
IO150NB7F14	L3
IO150PB7F14	L2
IO151NB7F14	K6
IO151PB7F14	L6
IO152NB7F14	K2
IO152PB7F14	K1
IO153NB7F14	K4
IO153PB7F14	K3
IO154NB7F14	H3
IO154PB7F14	J3
IO155NB7F14	H5
IO155PB7F14	J5
IO156NB7F14	H4
IO156PB7F14	J4
IO157NB7F14	H2
IO157PB7F14	J2
IO158NB7F15	H1
IO158PB7F15	J1
IO159NB7F15	F1
IO159PB7F15	G1
IO160NB7F15	F2
IO160PB7F15	G2
IO161NB7F15	H6
IO161PB7F15	J6
IO162NB7F15	F3
IO162PB7F15	G3

FG676



Note

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FG676	
AX500 Function	Pin Number
GND	R10
GND	R11
GND	R12
GND	R13
GND	R14
GND	R15
GND	R16
GND	R17
GND	T10
GND	T11
GND	T12
GND	T13
GND	T14
GND	T15
GND	T16
GND	T17
GND	U10
GND	U11
GND	U12
GND	U13
GND	U14
GND	U15
GND	U16
GND	U17
GND	V18
GND	V9
GND	W1
GND	W19
GND	W26
GND	W8
GND	Y20
GND	Y7
GND/LP	C2
NC	A11
NC	A21

FG676	
AX500 Function	Pin Number
NC	A22
NC	A24
NC	A25
NC	AA11
NC	AA19
NC	AA20
NC	AA4
NC	AA5
NC	AA6
NC	AA7
NC	AA8
NC	AA9
NC	AB1
NC	AB11
NC	AB17
NC	AB18
NC	AB19
NC	AB20
NC	AB8
NC	AB9
NC	AC1
NC	AC13
NC	AC14
NC	AC25
NC	AD1
NC	AD11
NC	AD16
NC	AD25
NC	AE1
NC	AF2
NC	AF25
NC	B11
NC	B24
NC	B4
NC	C16

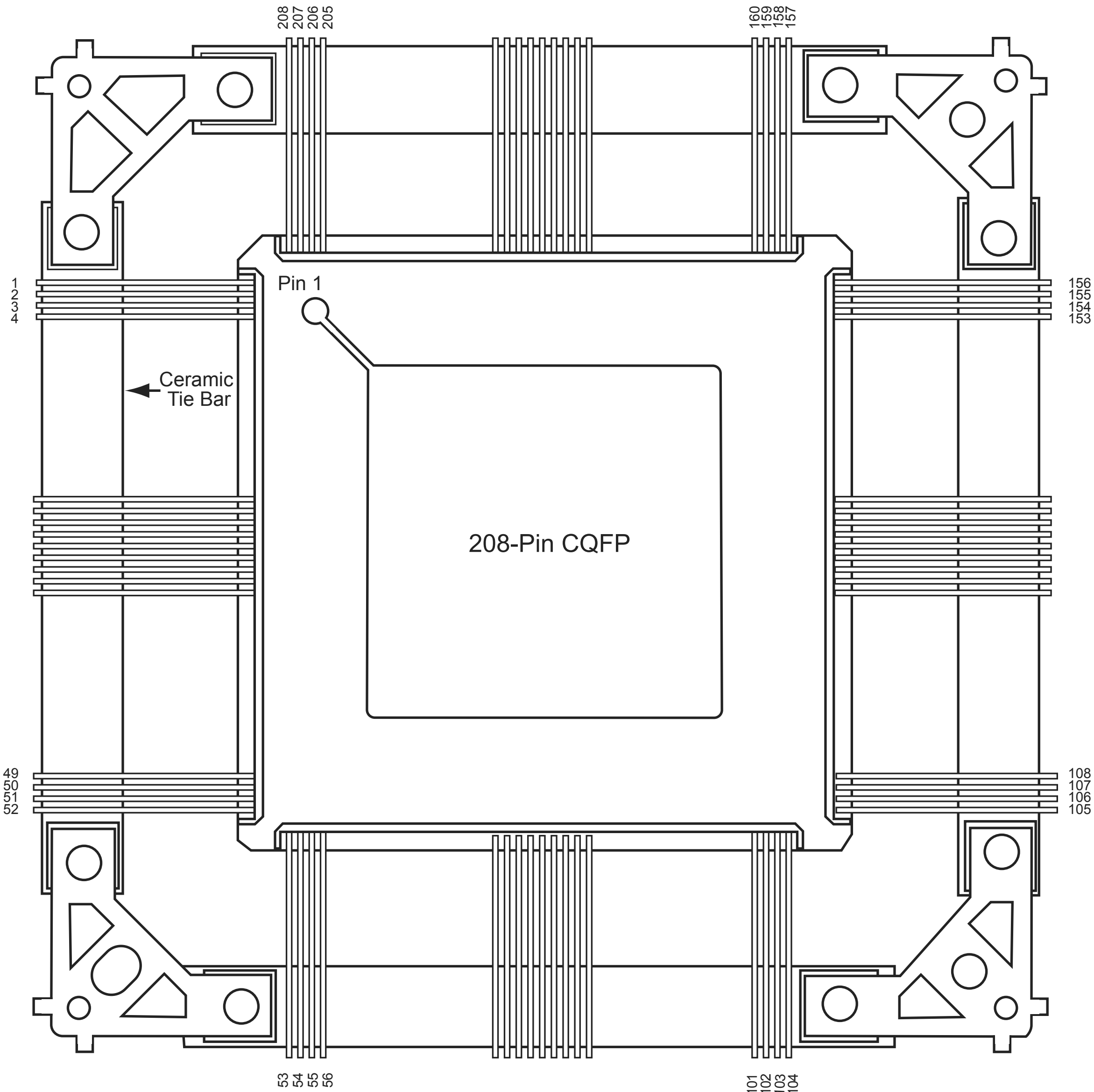
FG676	
AX500 Function	Pin Number
NC	C4
NC	D1
NC	D13
NC	D14
NC	D17
NC	D18
NC	D2
NC	D26
NC	D3
NC	D9
NC	E1
NC	E18
NC	E23
NC	E24
NC	E26
NC	E3
NC	E4
NC	E9
NC	F1
NC	F18
NC	F20
NC	F21
NC	F22
NC	F23
NC	F24
NC	F4
NC	F6
NC	F7
NC	G21
NC	G22
NC	H21
NC	H22
NC	H23
NC	H5
NC	H6

FG896	
AX2000 Function	Pin Number
IO180PB4F16	AG24
IO181NB4F17	AK24
IO181PB4F17	AK25
IO182NB4F17	AD22
IO182PB4F17	AC22
IO183NB4F17	AF22
IO183PB4F17	AF23
IO184NB4F17	AE21
IO184PB4F17	AE22
IO185NB4F17	AJ23
IO185PB4F17	AJ24
IO187NB4F17	AH22
IO187PB4F17	AH23
IO188NB4F17	AD21
IO188PB4F17	AC21
IO189PB4F17	AK22
IO190NB4F17	AF20
IO190PB4F17	AF21
IO191NB4F17	AG21
IO191PB4F17	AG22
IO192NB4F17	AE19
IO192PB4F17	AE20
IO195NB4F18	AK21
IO195PB4F18	AJ21
IO196NB4F18	AD19
IO196PB4F18	AD20
IO197NB4F18	AJ20
IO197PB4F18	AK20
IO198NB4F18	AC19
IO198PB4F18	AC20
IO199NB4F18	AG19
IO199PB4F18	AG20
IO200NB4F18	AH19
IO200PB4F18	AH20
IO201NB4F18	AK19

FG896	
AX2000 Function	Pin Number
IO201PB4F18	AJ19
IO202NB4F18	AC18
IO202PB4F18	AB18
IO206NB4F19	AE18
IO206PB4F19	AD18
IO207NB4F19	AJ17
IO207PB4F19	AJ18
IO208NB4F19	AE17
IO208PB4F19	AD17
IO209NB4F19	AK17
IO210NB4F19	AC17
IO210PB4F19	AB17
IO211NB4F19	AJ16
IO211PB4F19	AK16
IO212NB4F19/CLKEN	AG18
IO212PB4F19/CLKEP	AH18
IO213NB4F19/CLKFN	AG16
IO213PB4F19/CLKFP	AG17
Bank 5	
IO214NB5F20/CLKGN	AG14
IO214PB5F20/CLKGP	AG15
IO215NB5F20/CLKHN	AG13
IO215PB5F20/CLKHP	AH13
IO216NB5F20	AB14
IO216PB5F20	AC15
IO217NB5F20	AK15
IO217PB5F20	AJ15
IO218NB5F20	AE14
IO218PB5F20	AD14
IO219NB5F20	AK14
IO219PB5F20	AJ14
IO222NB5F20	AB13
IO222PB5F20	AC14
IO223NB5F21	AJ12
IO223PB5F21	AJ13

FG896	
AX2000 Function	Pin Number
IO225NB5F21	AH11
IO225PB5F21	AH12
IO226NB5F21	AC13
IO226PB5F21	AD13
IO227NB5F21	AE12
IO227PB5F21	AE13
IO228NB5F21	AG11
IO228PB5F21	AG12
IO229NB5F21	AK11
IO229PB5F21	AK12
IO230NB5F21	AC12
IO230PB5F21	AD12
IO232NB5F21	AE11
IO232PB5F21	AF11
IO233NB5F21	AJ10
IO233PB5F21	AJ11
IO234NB5F21	AC11
IO234PB5F21	AD11
IO236NB5F22	AK9
IO236PB5F22	AK10
IO237NB5F22	AG9
IO237PB5F22	AG10
IO238NB5F22	AF9
IO238PB5F22	AF10
IO239NB5F22	AH8
IO239PB5F22	AH9
IO240NB5F22	AC10
IO240PB5F22	AD10
IO242NB5F22	AE9
IO242PB5F22	AE10
IO243NB5F22	AJ7
IO243PB5F22	AJ8
IO244NB5F22	AK6
IO244PB5F22	AK7
IO245NB5F23	AF8

CQ208



Note

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CQ352	
AX250 Function	Pin Number
Bank 0	
IO00NB0F0	341
IO00PB0F0	342
IO01NB0F0	343
IO02NB0F0	337
IO02PB0F0	338
IO04NB0F0	335
IO04PB0F0	336
IO06NB0F0	331
IO06PB0F0	332
IO08NB0F0	325
IO08PB0F0	326
IO10NB0F0	323
IO10PB0F0	324
IO12NB0F0/HCLKAN	319
IO12PB0F0/HCLKAP	320
IO13NB0F0/HCLKBN	313
IO13PB0F0/HCLKBP	314
Bank 1	
IO14NB1F1/HCLKCN	305
IO14PB1F1/HCLKCP	306
IO15NB1F1/HCLKDN	299
IO15PB1F1/HCLKDP	300
IO16NB1F1	289
IO16PB1F1	290
IO17NB1F1	295
IO17PB1F1	296
IO18NB1F1	287
IO18PB1F1	288
IO20NB1F1	283
IO20PB1F1	284
IO22NB1F1	277
IO22PB1F1	278
IO23NB1F1	281
IO23PB1F1	282

CQ352	
AX250 Function	Pin Number
IO24NB1F1	275
IO24PB1F1	276
IO25NB1F1	271
IO25PB1F1	272
IO27NB1F1	269
IO27PB1F1	270
Bank 2	
IO29NB2F2	261
IO29PB2F2	262
IO30NB2F2	259
IO30PB2F2	260
IO31NB2F2	255
IO31PB2F2	256
IO33NB2F2	249
IO33PB2F2	250
IO34NB2F2	253
IO34PB2F2	254
IO35NB2F2	247
IO35PB2F2	248
IO36NB2F2	243
IO36PB2F2	244
IO37NB2F2	241
IO37PB2F2	242
IO38NB2F2	237
IO38PB2F2	238
IO39NB2F2	235
IO39PB2F2	236
IO41NB2F2	231
IO41PB2F2	232
IO42NB2F2	229
IO42PB2F2	230
IO43NB2F2	225
IO43PB2F2	226
IO44NB2F2	223
IO44PB2F2	224

CQ352	
AX250 Function	Pin Number
Bank 3	
IO45NB3F3	217
IO45PB3F3	218
IO46NB3F3	219
IO46PB3F3	220
IO47NB3F3	213
IO47PB3F3	214
IO48NB3F3	211
IO48PB3F3	212
IO49NB3F3	207
IO49PB3F3	208
IO51NB3F3	205
IO51PB3F3	206
IO52NB3F3	201
IO52PB3F3	202
IO53NB3F3	199
IO53PB3F3	200
IO54NB3F3	195
IO54PB3F3	196
IO55NB3F3	193
IO55PB3F3	194
IO56NB3F3	187
IO56PB3F3	188
IO57NB3F3	189
IO57PB3F3	190
IO59NB3F3	183
IO59PB3F3	184
IO60NB3F3	181
IO60PB3F3	182
IO61NB3F3	179
IO61PB3F3	180
Bank 4	
IO62NB4F4	172
IO62PB4F4	173
IO64NB4F4	166

CQ352	
AX1000 Function	Pin Number
Bank 0	
IO02NB0F0	341
IO02PB0F0	342
IO03PB0F0	343
IO04NB0F0	337
IO04PB0F0	338
IO08NB0F0	331
IO08PB0F0	332
IO09NB0F0	335
IO09PB0F0	336
IO24NB0F2	325
IO24PB0F2	326
IO25NB0F2	323
IO25PB0F2	324
IO30NB0F2/HCLKAN	319
IO30PB0F2/HCLKAP	320
IO31NB0F2/HCLKBN	313
IO31PB0F2/HCLKBP	314
Bank 1	
IO32NB1F3/HCLKCN	305
IO32PB1F3/HCLKCP	306
IO33NB1F3/HCLKDN	299
IO33PB1F3/HCLKDP	300
IO38NB1F3	295
IO38PB1F3	296
IO54NB1F5	287
IO54PB1F5	288
IO55NB1F5	289
IO55PB1F5	290
IO56NB1F5	281
IO56PB1F5	282
IO57NB1F5	283
IO57PB1F5	284
IO59NB1F5	277
IO59PB1F5	278

CQ352	
AX1000 Function	Pin Number
IO60NB1F5	275
IO60PB1F5	276
IO61NB1F5	271
IO61PB1F5	272
IO63NB1F5	269
IO63PB1F5	270
Bank 2	
IO64NB2F6	259
IO64PB2F6	260
IO67NB2F6	261
IO67PB2F6	262
IO68NB2F6	255
IO68PB2F6	256
IO69NB2F6	253
IO69PB2F6	254
IO74NB2F7	249
IO74PB2F7	250
IO75NB2F7	247
IO75PB2F7	248
IO76NB2F7	243
IO76PB2F7	244
IO77NB2F7	241
IO77PB2F7	242
IO78NB2F7	237
IO78PB2F7	238
IO79NB2F7	235
IO79PB2F7	236
IO82NB2F7	231
IO82PB2F7	232
IO83NB2F7	229
IO83PB2F7	230
IO94NB2F8	225
IO94PB2F8	226
IO95NB2F8	223
IO95PB2F8	224

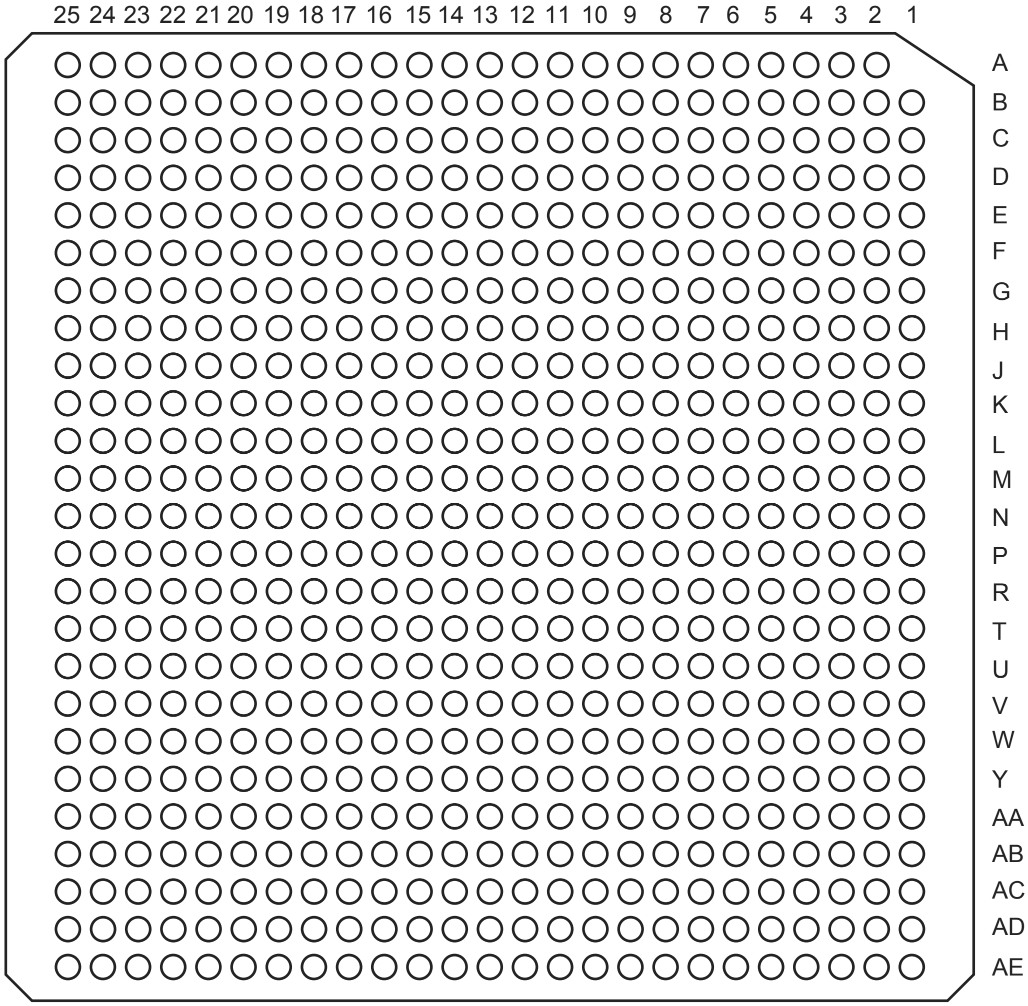
CQ352	
AX1000 Function	Pin Number
Bank 3	
IO96NB3F9	217
IO96PB3F9	218
IO97NB3F9	219
IO97PB3F9	220
IO99NB3F9	213
IO99PB3F9	214
IO108NB3F10	211
IO108PB3F10	212
IO109NB3F10	207
IO109PB3F10	208
IO111NB3F10	205
IO111PB3F10	206
IO112NB3F10	199
IO112PB3F10	200
IO113NB3F10	201
IO113PB3F10	202
IO115NB3F10	195
IO115PB3F10	196
IO116NB3F10	193
IO116PB3F10	194
IO117NB3F10	189
IO117PB3F10	190
IO124NB3F11	183
IO124PB3F11	184
IO125NB3F11	187
IO125PB3F11	188
IO127NB3F11	181
IO127PB3F11	182
IO128NB3F11	179
IO128PB3F11	180
Bank 4	
IO130NB4F12	172
IO130PB4F12	173
IO131NB4F12	170

CQ352	
AX2000 Function	Pin Number
GND	21
GND	27
GND	33
GND	39
GND	45
GND	51
GND	57
GND	63
GND	69
GND	75
GND	81
GND	88
GND	89
GND	97
GND	103
GND	109
GND	115
GND	121
GND	133
GND	145
GND	151
GND	157
GND	163
GND	169
GND	176
GND	177
GND	186
GND	192
GND	198
GND	204
GND	210
GND	216
GND	222
GND	228
GND	234

CQ352	
AX2000 Function	Pin Number
GND	240
GND	246
GND	252
GND	258
GND	264
GND	265
GND	274
GND	280
GND	286
GND	292
GND	298
GND	310
GND	322
GND	330
GND	334
GND	340
GND	345
GND	352
PRA	312
PRB	311
PRC	135
PRD	134
TCK	349
TDI	348
TDO	347
TMS	350
TRST	351
VCCA	3
VCCA	14
VCCA	32
VCCA	56
VCCA	74
VCCA	87
VCCA	102
VCCA	114

CQ352	
AX2000 Function	Pin Number
VCCA	150
VCCA	162
VCCA	175
VCCA	191
VCCA	209
VCCA	233
VCCA	251
VCCA	263
VCCA	279
VCCA	291
VCCA	329
VCCA	339
VCCDA	2
VCCDA	44
VCCDA	90
VCCDA	91
VCCDA	116
VCCDA	117
VCCDA	130
VCCDA	131
VCCDA	132
VCCDA	148
VCCDA	149
VCCDA	174
VCCDA	178
VCCDA	221
VCCDA	266
VCCDA	268
VCCDA	293
VCCDA	294
VCCDA	307
VCCDA	308
VCCDA	309
VCCDA	327
VCCDA	328

CG624



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